Pack Side Single Cell Fuel Gauge

General Description
The RT9422 Li-Ion/Li-Polymer battery fuel gauge is a microcontroller peripheral that provides fuel gauging for single-cell battery packs. The RT9422 resides within the battery pack and manages a non-removable battery or removable battery pack.

The RT9422 reports StateOfCharge, StateOfHealth, FullChargeCapacity, TimeToEmpty and CycleCount based on the Voltaic Gauge with Current Sensing (VGCS) algorithm by using the voltage difference between battery voltage and OCV to calculate the increasing or decreasing SOC, with current sensing compensation to report battery SOC.

Voltaic Gauge with Current Sensing algorithm can support smoothly SOC and does not accumulate error with time and current. That is an advantage compared to coulomb counter which suffer from SOC drift caused by current sense error and battery self-discharge.

The RT9422 provides complete battery status monitor with interrupt alarm function. It could alert to host processor actively when condition of battery over/under-voltage and over-temperature in charging/over-temperature in discharging. Especially for high C-rate battery charging application, it can measure battery voltage by kelvin sense connection to eliminate the IR drop effect for optimal charging profile and safety. More useful alarm functions are Under SOC alert and SOC Change.

The secondary safety features of the RT9422 can be used to indicate more serious faults via the SAFE pin. This pin can be used to blow an in-line fuse to permanently disable the battery pack from charging or discharging. The SAFE pin also can used to detect secondary protection IC status and log battery status in the NVM when protection be triggered.

To prevent battery pack cloning, the RT9422 integrates SHA-1/HMAC authentication with a 128-bit secret key.

Features
- Support Pack Side Fuel Gauging
- Battery Fuel Gauge for 1-Series (1sXp) Li-Ion/Li-Polymer Applications
- State of Charge (SOC) Calculated by VoltaicGauge™ with Current Sensing (VGCS)
- No Accumulation Error on Capacity Calculation
- Battery SOC, SOH, FCC, TTE and Cycle Count Report
- Voltage Measurement: ±7.5mV
- Current Measurement: ±1%
- Battery Temperature Measurement: ±3°C
- Battery Monitor with Alert Indicator for Voltage, Temperature and SOC
- Non Volatile Memory for Lifetime Logging, Battery Characterizing and Manufacturer Information Storage
- Battery Secondary Safety Protection
- SHA-1/HMAC for Battery Pack Authentication
- High C-Rate Battery Charging Compliance
- Low Power Consumption
- Low-Value Sense Resistor (2.5 to 20mΩ, Typical 10mΩ)
- 12 Pin WDFN Package with 0.4mm Pitch
- I2C Controlled Interface

Applications
- Smartphones
- Tablet PC
- Wearable Device
- Digital Still Cameras
- Digital Video Cameras
- Handheld and Portable Applications

Marking Information
02 : Product Code
W : Date Code
02W
Ordering Information

RT9422

Package Type
OW : WDFN-12L 2.5x4 (W-Type)

Lead Plating System
G : Green (Halogen Free and Pb Free)

Note:

Richtek products are:

- RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- Suitable for use in SnPb or Pb-free soldering processes.

Simplified Application Circuit
### Functional Pin Description

<table>
<thead>
<tr>
<th>Pin No.</th>
<th>Pin Name</th>
<th>Pin Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>SAFE</td>
<td>Output mode to enforce secondary safety protection; Input mode to detect output status of secondary protection IC.</td>
</tr>
<tr>
<td>2</td>
<td>VBATG</td>
<td>Battery voltage sensing negative input. Connect to battery connector with kelvin connection.</td>
</tr>
<tr>
<td>3</td>
<td>VDD</td>
<td>Power supply input.</td>
</tr>
<tr>
<td>4</td>
<td>VBATS</td>
<td>Battery voltage sensing positive input. Connect to battery connector with kelvin connection.</td>
</tr>
<tr>
<td>5</td>
<td>VPTS</td>
<td>Power reference output pin for temperature measurement.</td>
</tr>
<tr>
<td>6</td>
<td>VSS</td>
<td>Device ground.</td>
</tr>
<tr>
<td>7</td>
<td>CSP</td>
<td>Battery current sensing positive input. Connect a 10mΩ sense resistor with kelvin connection where is near BAT-side.</td>
</tr>
<tr>
<td>8</td>
<td>CSN</td>
<td>Battery current sensing negative input. Connect a 10mΩ sense resistor with kelvin connection where is near PACK-side.</td>
</tr>
<tr>
<td>9</td>
<td>TS</td>
<td>Temperature measurement input.</td>
</tr>
<tr>
<td>10</td>
<td>SDA</td>
<td>Serial data input. Slave (i^2C) serial communications data line for communication with system. Open-drain I/O.</td>
</tr>
<tr>
<td>11</td>
<td>SCL</td>
<td>Serial cock input. Slave (i^2C) serial communications clock line for communication with system. Open-drain I/O.</td>
</tr>
<tr>
<td>12</td>
<td>ALERT</td>
<td>Option for alert open-drain indicator output or single wire communication pin.</td>
</tr>
</tbody>
</table>

### Functional Block Diagram

```
VDD

VPTSo

TSo

VBATS o

VBATGo

CSP o

CSNo

ADC

VREF

VGCS Engine

Voltaic Gauge™

Current Sensing Compensation

Controller

Communication

NVM

ALERT

SDA

SCL

SAFE

VSS
```

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Absolute Maximum Ratings

- Voltage on CSN Pin to CSP
- Voltage on VBATS, VBATG, VPTS, TS to VSS
- Voltage on VDD Pin Relative to VSS
- Voltage on All Other Pins Relative to VSS
- Power Dissipation, P_D @ T_A = 25°C
  WDFN-12L 2.5x4
- Package Thermal Resistance
  WDFN-12L 2.5x4, θJA
  WDFN-12L 2.5x4, θJC
- Lead Temperature (Soldering, 10 sec.)
- Junction Temperature
- Storage Temperature Range
- ESD Susceptibility
  HBM (Human Body Model)

Recommended Operating Conditions

- Supply Voltage, VDD
- Ambient Temperature Range
- Junction Temperature Range

Electrical Characteristics

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operation Voltage</td>
<td>VDD - VSS</td>
<td></td>
<td>2.5</td>
<td>--</td>
<td>5.5</td>
<td>V</td>
</tr>
<tr>
<td>Active Current</td>
<td>I_ACTIVE</td>
<td>Active mode, VDD = 3.8V</td>
<td>--</td>
<td>14</td>
<td>20</td>
<td>μA</td>
</tr>
<tr>
<td>Sleep Current</td>
<td>I_SLEEP</td>
<td>Sleep mode, VDD = 3.8V</td>
<td>--</td>
<td>5</td>
<td>7</td>
<td>μA</td>
</tr>
<tr>
<td>Shutdown Current</td>
<td>I_SHUTDOWN</td>
<td>VDD = 3.8V</td>
<td>--</td>
<td>0.5</td>
<td>1</td>
<td>μA</td>
</tr>
<tr>
<td>Voltage Measurement Range</td>
<td></td>
<td></td>
<td>2.5</td>
<td>--</td>
<td>VDD</td>
<td>V</td>
</tr>
<tr>
<td>Voltage Measurement Error</td>
<td>V_ERR</td>
<td>VBATS = 4V, VBATG = 0V</td>
<td>−7.5</td>
<td>--</td>
<td>7.5</td>
<td>mV</td>
</tr>
<tr>
<td>Current Measurement Range</td>
<td></td>
<td>V_CSP - V_CSN</td>
<td>−125</td>
<td>--</td>
<td>125</td>
<td>mV</td>
</tr>
<tr>
<td>Current Measurement Error</td>
<td>I_ERR</td>
<td>Current = 1A, RSENSE = 10mΩ</td>
<td>−1</td>
<td>--</td>
<td>1</td>
<td>%</td>
</tr>
<tr>
<td>Temperature Measurement Error</td>
<td>ExtT_ERR</td>
<td>T_A = 25°C (Note 5)</td>
<td>−3</td>
<td>--</td>
<td>3</td>
<td>°C</td>
</tr>
<tr>
<td>Internal Temperature Measurement Range</td>
<td></td>
<td></td>
<td>−40</td>
<td>--</td>
<td>85</td>
<td>°C</td>
</tr>
<tr>
<td>Internal Temperature Measurement Error</td>
<td>IntT_ERR</td>
<td>T_A = 25°C</td>
<td>--</td>
<td>±3</td>
<td>--</td>
<td>°C</td>
</tr>
</tbody>
</table>
## Electrical Characteristics: I²C Interface

(2.5V ≤ VDD ≤ 4.5V, TA = 25°C, unless otherwise specified)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Clock Operating Frequency</td>
<td>fSCL</td>
<td>(Note 7)</td>
<td>10</td>
<td>--</td>
<td>400</td>
<td>kHz</td>
</tr>
<tr>
<td>Bus Free Time Between a STOP and START Condition</td>
<td>tBUF</td>
<td></td>
<td>1.3</td>
<td>--</td>
<td>--</td>
<td>μs</td>
</tr>
<tr>
<td>Hold Time After START Condition</td>
<td>tHD:STA</td>
<td>(Note 7)</td>
<td>0.6</td>
<td>--</td>
<td>--</td>
<td>μs</td>
</tr>
<tr>
<td>Low Period of the SCL Clock</td>
<td>tLOW</td>
<td></td>
<td>1.3</td>
<td>--</td>
<td>--</td>
<td>μs</td>
</tr>
<tr>
<td>High Period of the SCL Clock</td>
<td>tHIGH</td>
<td></td>
<td>0.6</td>
<td>--</td>
<td>--</td>
<td>μs</td>
</tr>
<tr>
<td>Setup Time for a Repeated START Condition</td>
<td>tSU:STA</td>
<td></td>
<td>0.6</td>
<td>--</td>
<td>--</td>
<td>μs</td>
</tr>
<tr>
<td>Data Hold Time</td>
<td>tHD:DAT</td>
<td>(Note 8, 9)</td>
<td>0.2</td>
<td>--</td>
<td>0.9</td>
<td>μs</td>
</tr>
<tr>
<td>Data Setup Time</td>
<td>tSU:DAT</td>
<td>(Note 8)</td>
<td>100</td>
<td>--</td>
<td>--</td>
<td>ns</td>
</tr>
<tr>
<td>Clock Data Rise Time</td>
<td>tR</td>
<td></td>
<td>20</td>
<td>--</td>
<td>300</td>
<td>ns</td>
</tr>
<tr>
<td>Clock Data Fall Time</td>
<td>tF</td>
<td></td>
<td>20</td>
<td>--</td>
<td>300</td>
<td>ns</td>
</tr>
</tbody>
</table>
### Table: Parameter Summary

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Set-up Time for STOP Condition</td>
<td>t_{SU:STO}</td>
<td></td>
<td>0.6</td>
<td>--</td>
<td>--</td>
<td>μs</td>
</tr>
<tr>
<td>Spike Pulse Widths Suppressed by Input Filter</td>
<td>t_{SP}</td>
<td>(Note 10)</td>
<td>0</td>
<td>--</td>
<td>50</td>
<td>ns</td>
</tr>
<tr>
<td>Capacitive Load for Each Bus Line</td>
<td>C_{B}</td>
<td>(Note 11)</td>
<td>--</td>
<td>--</td>
<td>400</td>
<td>pF</td>
</tr>
<tr>
<td>SCL, SDA Input Capacitance</td>
<td>C_{BIN}</td>
<td></td>
<td>--</td>
<td>--</td>
<td>60</td>
<td>pF</td>
</tr>
</tbody>
</table>

**Note 1.** Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

**Note 2.** \( \theta_{JA} \) is measured under natural convection (still air) at \( T_A = 25^\circ C \) with the component mounted on a high effective-thermal-conductivity four-layer test board on a JEDEC 51-7 thermal measurement standard. \( \theta_{JC} \) is measured at the top of the package.

**Note 3.** Devices are ESD sensitive. Handling precaution is recommended.

**Note 4.** The device is not guaranteed to function outside its operating conditions.

**Note 5.** The thermistor is use 10k NTC and beta 3435k, default is SEMITEC 103KT1608T.

**Note 6.** Specifications are 100% tested at \( T_A = 25^\circ C \). Limits over the operating range are guaranteed by design and characterization.

**Note 7.** \( t_{SCL} \) must meet the minimum clock low time plus the rise/fall times.

**Note 8.** The maximum \( t_{HD:DAT} \) has only to be met if the device does not stretch the low period (\( t_{LOW} \)) of the SCL signal.

**Note 9.** This device internally provides a hold time of at least 75ns for the SDA signal (referred to the \( V_{IHMIN} \)) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

**Note 10.** Filters on SDA and SCL suppress noise spikes at the input buffers and delay the sampling instant.

**Note 11.** \( C_{B} \) – total capacitance of one bus line in pF.

---

**I^2C Timing Diagram**

[Diagram of I^2C Timing](#)
Typical Application Circuit

- VDD
- SDA
- SCL
- Battery Protection Module
- CSP
- CSN
- VBAT
- VBATG
- SAFE
- VPTS
- C1: 1µF
- R1: 10kΩ (optional)
- C6: 10nF
- TS
- VBATG
- CSP
- CSN
- R3: 10Ω
- R4: 100Ω
- R5: 100Ω
- R6: 100Ω
- R7: 100Ω
- R8: 100Ω
- R9: 100Ω
- R10: 100Ω
- R11: 100Ω
- C3: 0.1µF
- C4: 0.1µF
- C5: 0.1µF
- R2: 51kΩ
- C7: 0.1µF
- NMOS
- PACK+
- FUSE
- IO Power
- SYSTEM
- PACK-
Typical Operating Characteristics

* : Sample accuracy with custom parameter into the IC.

Voltage ADC Error vs. Temperature

Current ADC Error vs. Temperature

Temperature Measurement Error vs. Temperature

SOC Accuracy*
Application Information

ADC for Voltage, Current and Temperature

Battery voltage is measured at the VBATS pin input with respect to VBATG over a 2.5 to 5.5V range with resolutions of 1mV. The ADC calculates the first cell voltage for a period of 250ms after IC POR and then for a period of 1s for every cycle afterwards. The Voltage register requires 1s to update after exiting Sleep mode. The result is placed in the Voltage register at the end of each conversion period.

The RT9422 Fuel Gauge measures battery current in charging and discharging and reports it to Current register. The measurement range is 10A (RS = 10mΩ), and the resolution is 1mA.

The RT9422 reports temperature to Temperature register by measuring battery temperature or chip temperature. When measuring battery temperature, an external NTC resistor will be used.

**VoltaicGauge™ with Current Sensing (VGCS) Algorithm**

The VGCS algorithm is based on the battery voltage and the dynamic difference of battery voltage and battery current measurement, by iterating battery voltage information and compensating with current information to increase or decrease delta SOC, then integrate to SOC. The below figure is for VGCS functional block.

The RT9422 got battery voltage information then using OCV table and iterate calculation with current correction to calculate delta SOC, then using design capacity and battery capacity as a reference to optimize result and output final SOC result. VGCS also support high C-RATE charging technology.

The coulomb counter based fuel gauge suffers from SOC drift due to current-sense error and cell self-discharge. Even there is a very small current sensing error, the coulomb counter accumulates the error from time to time, VGCS is based on voltage iteration algorithm to reach stable SOC behavior and only using current information to fine tune result for getting good transient state response. VGCS does not accumulate current and suffer SOC drift issue like traditional coulomb counter.

**Design Capacity**

The DesignCapacity register should be set with proper value after IC POR, Design Capacity is the expected capacity when cell has been made and it's not been changed when VGCS active. Design Capacity is used as a reference input for VGCS algorithm. The resolution of Design Capacity is 1mAh and default value is 0x079E (1950mAh).

**SOC Report**

The StateOfCharge register is a read-only register that displays the state of charge of the cell as calculated by the VGCS algorithm. The result is displayed as a percentage of the cell’s full capacity. This register automatically adapts to variation in battery size since the Fuel Gauge naturally recognize relative SOC. The
units of SOC is %. The reported SOC also includes residual capacity, which might not be available to the actual application because of early termination voltage requirements. When SOC = 0, typical applications have no remaining capacity. The first update occurs in 250ms after POR of the IC.

**Power Mode**

There are three power mode for the RT9422. Each power mode could be applied on different application for different power consumption considering. The three power modes are Active mode, Sleep mode and Shutdown mode.

**Active Mode**

The active mode is recommended and it is the default power mode after POR. In active mode, the Voltage, Current, Temperature, Average Voltage, Average Current and Average Temperature will be updated every second.

**Sleep Mode**

The sleep mode behavior is same as the active mode but it has the longer measurement period. The period in the sleep mode is programmable. The minimum period is 2 times of active mode and the maximum period is 16 times of active mode. The default period is 4 times of active mode. When sleep mode function is enabled, it could be entered/exit by sending commands or by Fuel Gauge self-detection.

**Shutdown Mode**

In shutdown mode the RT9422 will stop all measurement behaviors and stop to update registers to keep the minimum power consumption. To enter shutdown mode, the function should be enabled first. Then, it could be entered by either sending command or pulling low I²C bus.

To exit shutdown mode, an exit shutdown command should be received when it’s entered by command. Otherwise, the I²C bus should be pulled high when it’s entered by I²C bus low condition.

---

**Power Mode Switching**

<table>
<thead>
<tr>
<th>POR</th>
<th>Active</th>
<th>Sleep</th>
<th>Shutdown</th>
</tr>
</thead>
<tbody>
<tr>
<td>1. Exit shutdown command</td>
<td>Disable Sleep Mode &amp; 1. Exit sleep command or 2. FG self-detected exit</td>
<td>Enable Sleep Mode &amp; 1. Entry sleep command or 2. FG self-detected entry</td>
<td></td>
</tr>
<tr>
<td>2. I²C pull high</td>
<td></td>
<td></td>
<td>1. Exit shutdown command</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>2. I²C pull high</td>
</tr>
</tbody>
</table>

**Controller**

The controller takes care of the control flow of system routine, ADC measurement flow, algorithm calculation and alert determined.

**Power Up Sequence**

When the RT9422 is power on, the Fuel Gauge (FG) measures the battery voltage and then predicts the first SOC according to the voltage for a period of 250ms. The first SOC would be accurate if the battery has been well relaxed for over 30 minutes. Otherwise, the initial SOC error occurs. However, the initial SOC error will be convergent and the SOC will be adjusted gradually and finally approach to the OCV when battery is relaxed.

**Quick Sensing**

A Quick Sensing operation allows the RT9422 to restart battery voltage sensing and StateOfCharge calculation. The operation is used to reduce the initial StateOfCharge error caused by improper power-on sequence. A Quick Sensing operation could be performed by I²C Quick Sensing command (0x4000) to the Control register.

**Battery Secondary Safety Protection**

The RT9422 device can permanently disable the use of the battery pack in case of failure of Safety Cell Over-Voltage Protection, Safety Over-Current in Charge Protection, Safety Over-Current in Discharge Protection and Safety Over-Temperature Protection.

**Authentication**
The RT9422 device can act as a SHA-1/HMAC authentication slave by using its internal engine. Sending a 160-bit SHA-1 challenge message to the RT9422 causes to return a 160-bit digest, based upon the challenge message and a hidden, 128-bit plain-text authentication key. If this digest matches an identical one generated by a host or dedicated authentication master, and when operating on the same challenge message and using the same plain text keys, the authentication process is successful.

Alert Function

The RT9422 support several kinds of alert to alarm system there is abnormal condition need to be noticed, such as over temperature or under voltage. It total includes over-temperature in charge (OTC), over-temperature in discharge (OTD), over-voltage (OV), under-voltage (UV), under-SOC (US) and SOC change (SC).

Host can polling the ALERT Flag for a period to monitor system status or accept the interrupt notice from the RT9422 ALERT pin. Alert need to be enabled before it works. There are 2 ways to enable alert function. One is to enable specified bit operation, the other is just to set a proper value to detection threshold. Please refer to below diagram and descriptions for detailed.

---

**Figure 1. ALERT Function Timing Diagram**

1. ALERT occur but ALERT_EN is disabled, ALERT FLAG have no response.
2. ALERT_EN enable, ALERT FLAG is set when ALERT condition occur.
3. ALERT FLAG is cleared when ALERT condition recover.
4. When ALERT FLAG is already set and IRQ_EN is set, IRQ and ALERT PIN output have no response.
5. IRQ is set and ALERT PIN output low only when IRQ_EN is set and ALERT FLAG state change.
6. IRQ and ALERT PIN are read clear only.
7. Clear IRQ_EN have no effect on IRQ and ALERT PIN output.
8. Disable ALERT_EN will also clear ALERT FLAG.

---

Figure 2. SC ALERT Function Timing Diagram

1. ALERT condition occur but ALERT_EN disable, ALERT FLAG have no response.
2. ALERT_EN enable, ALERT FLAG is set when ALERT condition occur.
3. ALERT FLAG is cleared when driver write ALERT_FLAG to 0.
4. When ALERT_FLAG is already set and IRQ_EN is set, IRQ and ALERT PIN output have no response.
5. IRQ is set and ALERT PIN output low only when IRQ_EN is set and ALERT_FLAG state set.
6. IRQ and ALERT PIN are read clear only, driver read clear IRQ will also clear ALERT FLAG
7. Clear IRQ_EN have no effect on IRQ and ALERT PIN output.
8. Disable ALERT_EN will also clear ALERT_FLAG.
I²C Interface

The RT9422 I²C slave address = 7'b1010101. I²C interface support fast mode (bit rate up to 400kb/s). The write or read bit stream is shown below:

Read data from the RT9422

Write data to the RT9422

Register Summary Table

<table>
<thead>
<tr>
<th>Name</th>
<th>Symbol</th>
<th>Address</th>
<th>Unit</th>
<th>Mode</th>
<th>Reset</th>
</tr>
</thead>
<tbody>
<tr>
<td>Control</td>
<td>CNTL</td>
<td>0x00 to 0x01</td>
<td>--</td>
<td>R/W</td>
<td>0x0000</td>
</tr>
<tr>
<td>Current</td>
<td>CURR</td>
<td>0x04 to 0x05</td>
<td>mA</td>
<td>R</td>
<td>0x0000</td>
</tr>
<tr>
<td>Temperature</td>
<td>TEMP</td>
<td>0x06 to 0x07</td>
<td>0.1°K</td>
<td>R</td>
<td>0x0BA6</td>
</tr>
<tr>
<td>Voltage</td>
<td>VBAT</td>
<td>0x08 to 0x09</td>
<td>mV</td>
<td>R</td>
<td>0x0ED8</td>
</tr>
<tr>
<td>Flag1</td>
<td>FLAG1</td>
<td>0x0A to 0x0B</td>
<td>--</td>
<td>R</td>
<td>0x0000</td>
</tr>
<tr>
<td>Flag2</td>
<td>FLAG2</td>
<td>0x0C to 0x0D</td>
<td>--</td>
<td>R</td>
<td>0x0000</td>
</tr>
<tr>
<td>RemainingCapacity</td>
<td>RM</td>
<td>0x10 to 0x11</td>
<td>mAh</td>
<td>R</td>
<td>0x03CF</td>
</tr>
<tr>
<td>FullChargeCapacity</td>
<td>FCC</td>
<td>0x12 to 0x13</td>
<td>mAh</td>
<td>R</td>
<td>0x079E</td>
</tr>
<tr>
<td>AverageCurrent</td>
<td>AI</td>
<td>0x14 to 0x15</td>
<td>mA</td>
<td>R</td>
<td>0x0000</td>
</tr>
<tr>
<td>TimeToEmpty</td>
<td>TTE</td>
<td>0x16 to 0x17</td>
<td>minute</td>
<td>R</td>
<td>0xFFFF</td>
</tr>
<tr>
<td>Version</td>
<td>VER</td>
<td>0x20 to 0x21</td>
<td>--</td>
<td>R</td>
<td>0x0001</td>
</tr>
<tr>
<td>VGCOMP12</td>
<td>VGCOMP12</td>
<td>0x24 to 0x25</td>
<td>--</td>
<td>R/W</td>
<td>0x3232</td>
</tr>
<tr>
<td>VGCOMP34</td>
<td>VGCOMP34</td>
<td>0x26 to 0x27</td>
<td>--</td>
<td>R/W</td>
<td>0x3232</td>
</tr>
<tr>
<td>InternalTemperature</td>
<td>INTT</td>
<td>0x28 to 0x29</td>
<td>0.1°K</td>
<td>R</td>
<td>0x0BA6</td>
</tr>
<tr>
<td>CycleCount</td>
<td>CYC</td>
<td>0x2A to 0x2B</td>
<td>Counts</td>
<td>R/W</td>
<td>0x0000</td>
</tr>
<tr>
<td>StateOfCharge</td>
<td>SOC</td>
<td>0x2C to 0x2D</td>
<td>%</td>
<td>R</td>
<td>0x0021</td>
</tr>
<tr>
<td>StateOfHealth</td>
<td>SOH</td>
<td>0x2E to 0x2F</td>
<td>%</td>
<td>R</td>
<td>0x0064</td>
</tr>
<tr>
<td>Flag3</td>
<td>FLAG3</td>
<td>0x30 to 0x31</td>
<td>--</td>
<td>R</td>
<td>0x0000</td>
</tr>
<tr>
<td>IRQ</td>
<td>IRQ</td>
<td>0x36 to 0x37</td>
<td>--</td>
<td>R</td>
<td>0x0000</td>
</tr>
<tr>
<td>DesignCapacity</td>
<td>DC</td>
<td>0x3C to 0x3D</td>
<td>mAh</td>
<td>R</td>
<td>0x079E</td>
</tr>
<tr>
<td>ExtendedControl</td>
<td>EXTDCNTL</td>
<td>0x3E to 0x3F</td>
<td>--</td>
<td>R/W</td>
<td>0x0000</td>
</tr>
<tr>
<td>AverageVoltage</td>
<td>AV</td>
<td>0x64 to 0x65</td>
<td>mV</td>
<td>R</td>
<td>0x0ED8</td>
</tr>
<tr>
<td>AverageTemperature</td>
<td>AT</td>
<td>0x66 to 0x67</td>
<td>0.1°K</td>
<td>R</td>
<td>0x0BA6</td>
</tr>
</tbody>
</table>
Thermal Considerations

The junction temperature should never exceed the absolute maximum junction temperature $T_{J(MAX)}$, listed under Absolute Maximum Ratings, to avoid permanent damage to the device. The maximum allowable power dissipation depends on the thermal resistance of the IC package, the PCB layout, the rate of surrounding airflow, and the difference between the junction and ambient temperatures. The maximum power dissipation can be calculated using the following formula:

$$P_{D(MAX)} = \frac{(T_{J(MAX)} - T_A)}{\theta_{JA}}$$

where $T_{J(MAX)}$ is the maximum junction temperature, $T_A$ is the ambient temperature, and $\theta_{JA}$ is the junction-to-ambient thermal resistance.

For continuous operation, the maximum operating junction temperature indicated under Recommended Operating Conditions is 125°C. The junction-to-ambient thermal resistance, $\theta_{JA}$, is highly package dependent. For a WDFN-12L 2.5x4 package, the thermal resistance, $\theta_{JA}$, is 38.8°C/W on a standard JEDEC 51-7 high effective-thermal-conductivity four-layer test board. The maximum power dissipation at $T_A = 25^\circ$C can be calculated as below:

$$P_{D(MAX)} = \frac{(125^\circ$C - 25$^\circ$C)}{(38.8$^\circ$C/W)} = 2.57W$$

for a WDFN-12L 2.5x4 package.

The maximum power dissipation depends on the operating ambient temperature for the fixed $T_{J(MAX)}$ and the thermal resistance, $\theta_{JA}$. The derating curves in Figure 3 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

![Derating Curve of Maximum Power Dissipation](image)

Layout Considerations

To ensure the measurement accuracy of the RT9422, the recommended layout guideline is as below:

- The capacitor of VBATS and VDD pins must be put as close as possible to avoid the noise effect.
- The VBATS and VBATG path must be make Kelvin Sense connection to the $B+$ and $B-$ to minimize the IR drop effect on voltage measurement accuracy.
- The CSN and CSP path must be make Kelvin Sense connection to RS to avoid the IR drop effect on current measurement accuracy.
- The NTC should be as close as possible to the Battery and far away from the thermal area.
- There are no special layout requirements for other pins.
Capacitor must be placed as close as possible to the input pins.

Mount the RS as close as possible to B- and using Kelvin sense layout style to avoid IR drop.

C2/C3/C4 ground path connect together and as short as possible.

Place the chip as close as possible to the battery.

Figure 4. PCB Layout Guide
Outline Dimension

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Dimensions in Millimeters</th>
<th>Dimensions in Inches</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Min</td>
<td>Max</td>
</tr>
<tr>
<td>A</td>
<td>0.700</td>
<td>0.800</td>
</tr>
<tr>
<td>A1</td>
<td>0.000</td>
<td>0.050</td>
</tr>
<tr>
<td>A3</td>
<td>0.175</td>
<td>0.250</td>
</tr>
<tr>
<td>b</td>
<td>0.150</td>
<td>0.250</td>
</tr>
<tr>
<td>D</td>
<td>2.400</td>
<td>2.600</td>
</tr>
<tr>
<td>D2</td>
<td>1.950</td>
<td>2.050</td>
</tr>
<tr>
<td>E</td>
<td>3.900</td>
<td>4.100</td>
</tr>
<tr>
<td>E2</td>
<td>2.450</td>
<td>2.550</td>
</tr>
<tr>
<td>e</td>
<td>0.400</td>
<td>0.450</td>
</tr>
<tr>
<td>L</td>
<td>0.350</td>
<td>0.450</td>
</tr>
</tbody>
</table>

W-Type 12L DFN 2.5x4 Package

Note: The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.
## Footprint Information

<table>
<thead>
<tr>
<th>Package</th>
<th>Number of Pin</th>
<th>Footprint Dimension (mm)</th>
<th>Tolerance</th>
</tr>
</thead>
<tbody>
<tr>
<td>V/W/U/XDFN2.5x4-12</td>
<td>12</td>
<td>P 0.40  A 4.80  B 3.10  C 0.85  D 0.20  Sx 2.50  Sy 2.50  M 2.20</td>
<td>±0.05</td>
</tr>
</tbody>
</table>